

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim11 (currently amended): A method for removing adhesive coatings from a plurality of substrates having dense submicron topography containing prominent sidewalls, comprising the steps of:

~~placing a quartz gas distribution plate, connected to a pressure regulated gas supply, in a tank containing a liquid chemical;~~

~~submerging and placing a substrate carrier, containing a plurality of substrates, on said quartz gas distribution plate so that said substrates are aligned and in a vertical position relative to said quartz gas distribution plate;~~

~~said quartz distribution plate directs gas bubbles between and parallel to each surface of said substrates aligned thereabove, said gas distribution plate providing a chemical mechanical scrubbing;~~

~~removing said substrate carrier from said chemical liquid.~~

providing a substrate carrier containing a plurality of substrates;

providing a tank containing a liquid chemical;

placing a quartz gas distribution plate on bottom of said tank, said quartz gas distribution plate having trough means for guiding a flexible tubing and drill

guide means for drilling a linear array of holes in said guided flexible tubing.  
said flexible tubing connected to a pressure regulated gas supply;  
positioning said substrate carrier on said quartz gas distribution plate so that a  
linear array of gas bubbles flowing upwards scrub surfaces between each  
substrate.

Claim 12 (currently amended): The method according to claim 11 wherein trough  
and drill guide means ~~quartz gas distribution plate having~~ providing ~~distribution means~~  
~~for generating an array~~ a plurality of linear of gas bubbles, ~~each row of said array patterns~~  
~~that correspond~~[[ing]] to each [[a]] ~~substrate position of said~~ contained in said substrate  
carrier.

Claim 13 (original): The method according to claim 11 wherein said pressure  
regulated gas supply is nitrogen gas.

Claim 14. (currently amended): The method according to claim 11 wherein ~~using~~ a  
quartz gas distribution plate with a flexible tubing are each [[is]] compatible with  
aggressive chemicals used for removing adhesive residues in metal sidewalls that are  
coated with polymer.

Claim 15. (currently amended) A method for stripping adhesive photoresist from a  
plurality of semiconductor wafers having dense submicron topography containing

prominent sidewalls, comprising the steps of:

providing a wafer cassette containing a plurality of wafers;

providing a tank containing a photoresist stripping chemical;

providing a quartz gas distribution plate and placing it on bottom of said tank, said

quartz gas distribution plate having trough means for guiding a flexible tubing

and drill guide means for drilling a linear array of holes in said guided flexible

tubing, said flexible tubing connected to a pressure regulated gas supply;

positioning said wafer cassette on said quartz gas distribution plate so that a

linear array of gas bubbles emanating from holes drilled in said flexible tubing,

flow upwards, therein scrubbing the surfaces of each wafer.

~~horizontally placing a quartz gas distribution plate, connected to a pressure-~~

~~regulated nitrogen supply, in an open tank containing a photoresist stripping  
chemical;~~

~~submerging and placing a wafer cassette containing a plurality of wafers on said~~

~~quartz gas distribution plate so that said wafers are aligned and in a vertical~~

~~position relative to said quartz gas distribution plate;~~

~~said distribution plate directs nitrogen bubbles between and parallel to each~~

~~surface of said wafers aligned thereabove, said nitrogen bubbles providing a  
chemical-mechanical scrubbing;~~

~~removing said wafer cassette from said photoresist stripping liquid.~~

Claim 16. (currently amended): The method according to claim 15 wherein said

quartz gas distribution plate having a gas distribution pattern means for generating [[an]]  
rows array of nitrogen bubbles, each row of said array corresponding to a wafer position  
contained in said wafer cassette.

Claim 18. (currently amended): The method according to claim 15 wherein using  
a quartz gas distribution plate and flexible tubing that are [[is]] compatible with aggressive  
chemicals for removing adhesive residues in metal sidewalls that are coated with adhesive  
photoresist.

Claim 19. (new): The method according to claim 15 wherein said pressure  
regulated gas supply is nitrogen gas.